

ABSTRACT OF THE DISCLOSURE

A surface of an external electrode 3 of an electronic part 4 is formed with a coating containing resin ingredient. Thereby, adhesion strength and reliability may be significantly improved in mounting an electronic part onto a circuit board 1 through the medium of a conductive adhesive. Further, it will be able to mount an electronic part to an element to be mounted by utilizing a conductive adhesive forming an external electrode 3 as a connecting element.

Further, surface roughness (R_a) of an external electrode 3 of an electronic part is set to 0.1 μm or more and to 10.0 μm or less and preferably to 1.0 μm or more and to 5.0 μm or less. Thereby, adhesion strength with a conductive adhesive may be significantly enhanced in comparison with a conventional electronic part presented.